



<b>Session Title:</b>	<b>[MD1] Novel Etch Technology</b>
<b>Session Date:</b>	<b>November 20 (Mon.), 2023</b>
<b>Session Time:</b>	<b>13:00-14:30</b>
<b>Session Room:</b>	<b>Room D (Grand Ballroom 3, 2F)</b>
<b>Session Chair:</b>	<b>Prof. Gottlieb S. Oehrlein (Univ. of Maryland, USA)</b>

**[MD1-1]** **13:00-13:20**

**Low-Energy Electron Beam Assisted Etching in Inductively Coupled Plasma**

Jiwon Jung, Min-Seok Kim, Junyoung Park, and Chin Wook Chung (Hanyang Univ., Korea)

**[MD1-2]** **13:20-13:40**

**Reactive Proton Assisted Etching for Cu and Ni Alloy Dry Etching**

MunPyo Hong, Minyoung Kim, Donghoon Kim (Korea Univ., Korea), Sangheon Lee, JongHwa Lee, JinNyoung Jang, Chiwoo Kim (APS Research Corp., Korea), and Sang-Gab Kim (Samsung Display Co., Ltd., Korea)

**[MD1-3]** **13:40-14:00**

**Characteristics of Segmented-Dielectric Window Inductively Coupled Plasma**

Sang-Woo Kim (Pusan Nat'l Univ., Korea), Ju-Hong Cha (Gyeongsang Nat'l Univ., Korea), and Ho-Jun Lee (Pusan Nat'l Univ., Korea)

**[MD1-4] [Invited]** **14:00-14:30**

**Cryogenic Etching Processes Applied to the Next Generation of Nanoelectronic Technologies**

R. Dussart, T. Tillocher, G. Antoun, J. Nos, R. Ettouri, and P. Lefauchaux (GREMI Univ. of Orleans CNRS, France)